

**Amendments to the Specification:**

Please replace the first paragraph of the Detailed Description beginning on line 2 of page 5 with the following amended paragraph:

Fig. 1 is a perspective three-dimensional view of a PC board 10 including a substrate 12 having a first surface 14 and a second surface 16. A plurality of vias 18 is formed in the substrate 12 in a manner known in the art. In the preferred embodiment of the invention, vias 18 extend from first surface 14, through the substrate 12 to the second surface 16. A plurality of electrically conductive layers 20 are disposed within the substrate 20 to deliver power voltage to the power vias [[16]] 18, ground voltage to the ground vias [[16]] 18 and the to interconnect the signal vias 18. In use, an IC device (not shown), such as a field programmable gate array (FPGA), is mounted to the first surface 14 of the substrate 12 via the BGA. The number of vias shown in the board 10 of Fig. 1 is for example only and it will be understood that any number of vias may be included in a particular PC board.